



# You are Invited!

**TRI will showcase latest PCBA testing and inspection technologies at NEPCON China 2015 show in Hall 1 of Shanghai World Expo & Convention Center. Visit booth **B-1F20** from **April 21~23** to see latest news in industry's only complete portfolio for testing and inspection.**

## New SPI!

### TR7007Q

- Stop-and-Go 3D SPI
- Digital 3D Projection
- Ultra High Accuracy
- SmartWarp Correction

### TR7500 SIII 3D

## Fastest 3D!

- Leading 3D AOI Speed
- Total 2D + 3D Coverage
- 5 Color Cameras
- Automotive + HDI

### TR7007 SII Plus

- Ultimate 3D SPI
- Industry Leading Speed
- Ultra High Accuracy
- Closed Loop Integration

### TR7700 SII Plus

- Dynamic + Stop & Go Imaging
- 5 Color Cameras
- Automotive + HDI

### TR7600LL SII

- High Speed Inline 3D X-ray Inspection
- Planar 3D CT Upgrade
- PCB up to 1000x660 mm
- Easy CAD & CAD-free programming
- BGA, LGA, PoP, PTH, QFN inspection

### TR7700 SIII DT

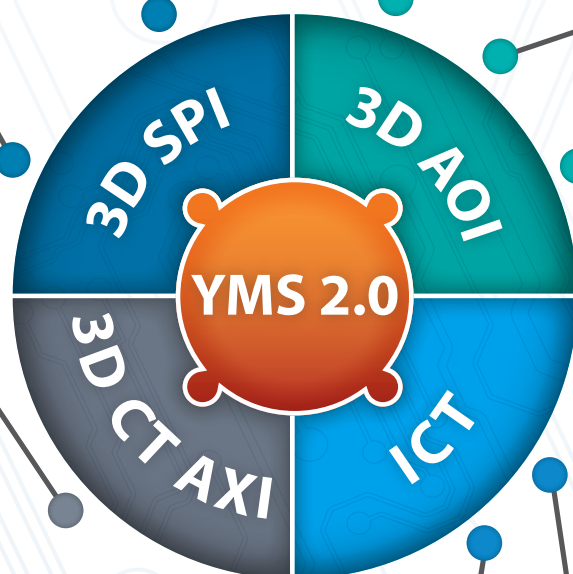
- High Performance AOI
- 100 mm PCB Clearance
- 10/15  $\mu$ m Resolution
- NPI Optimized System

### TR5001 INLINE

- Modular MDA/ICT System
- Bosch CM Exclusive ICT
- SMEMA Standard INLINE
- Boundary Scan Solution

### TR5001 SII TINY

- Most Powerful TINY ICT
- Parallel Testing
- Fast Programming
- New Software UI!



**Come see us at B-1F20 (Hall 1)**

**TRI**  
 innovation